

ABSTRACT OF THE DISCLOSURE

A thermally-conductive epoxy resin molded article
conducting heat generated from electronic components and the
5 like, and a method of manufacturing the same are disclosed.
The thermally-conductive epoxy resin molded article
according to the present invention is obtained by curing an
epoxy resin composition containing an epoxy resin. The epoxy
resin contained in the thermally-conductive epoxy resin
10 molded article has the degree of orientation α equal to or
larger than 0.5 and smaller than 1.0. The degree of
orientation α is determined by the following equation:

$$\text{degree of orientation } \alpha = (180 - \Delta\beta)/180 \dots (1)$$

wherein $\Delta\beta$ represents a half-width of a peak in an intensity
15 distribution measured by fixing to a peak scattering angle
in an x-ray diffraction measurement, and then changing an
azimuth angle from 0 degree to 360 degrees.